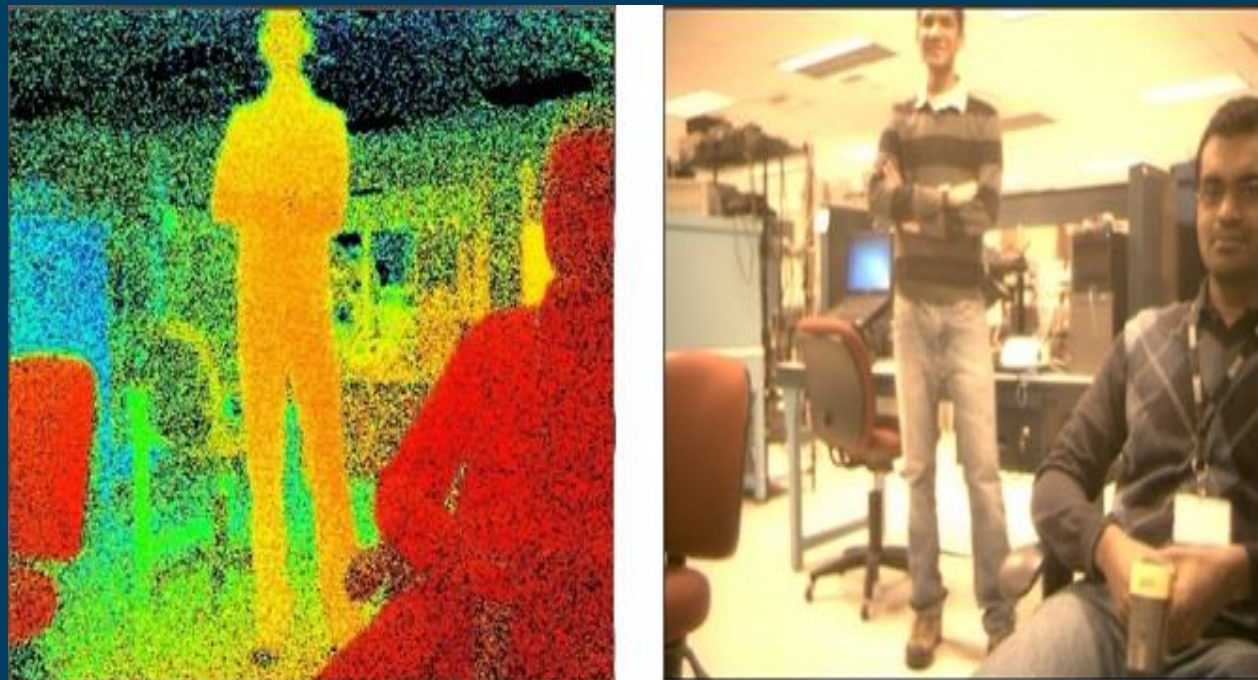
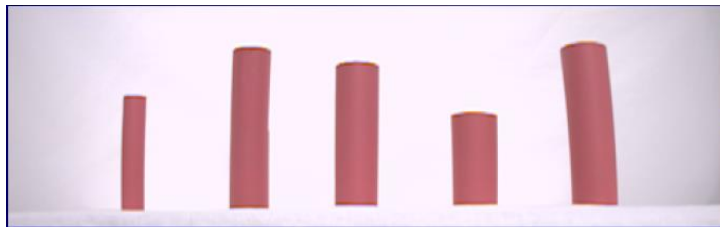


ADI 3D DEPTH SENSING

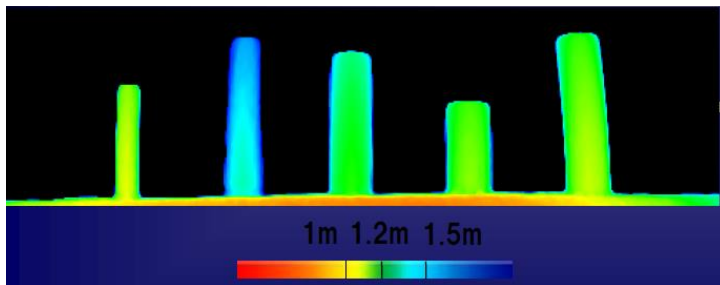


3D Depth Mapping

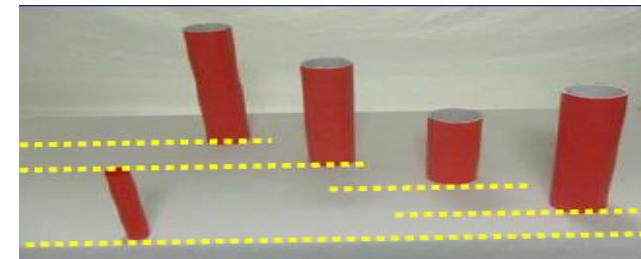
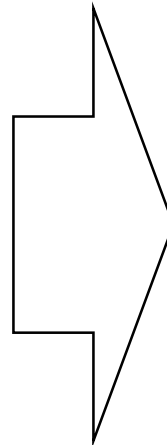
- ▶ Enables the user to get a human-scale understanding of its environment in the 3rd dimension - i.e., it would make the camera aware of its surroundings in terms of *how far away* the objects are as well as the *actual mass* or *scale* of each of those objects.
- ▶ Example: which pole is closest to the camera?



RGB Camera



Depth Detection Camera



Distances between the dotted yellow lines can be measured

Depth Maps

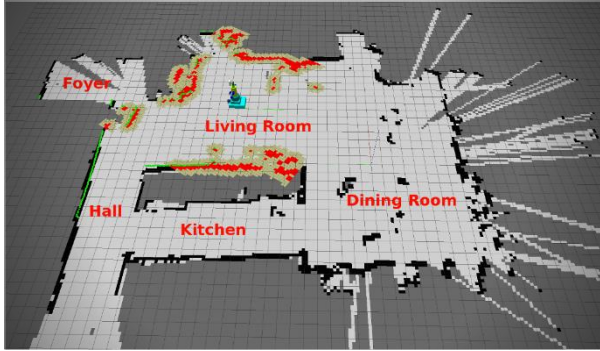
Photographed Image



Distance Image



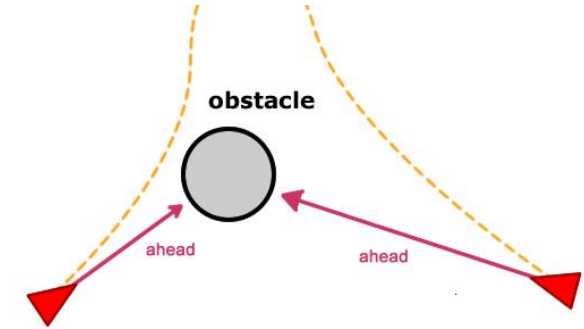
3D Depth Mapping Use Cases



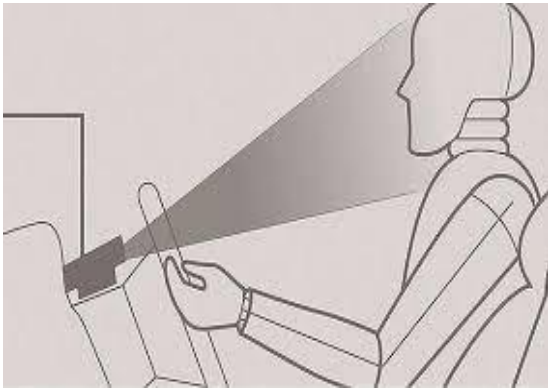
SLAM (Simultaneous Location and Mapping)



Gesture Control



Object Avoidance



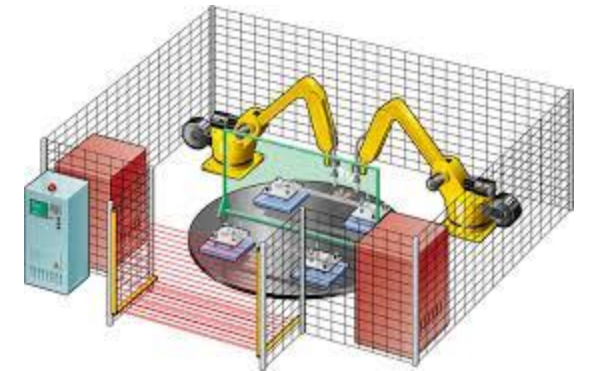
DMS / Passenger monitoring



People Counting



3D scanning



Safety / Proximity Sensing

3D Depth Mapping Applications



AR/VR



Drones



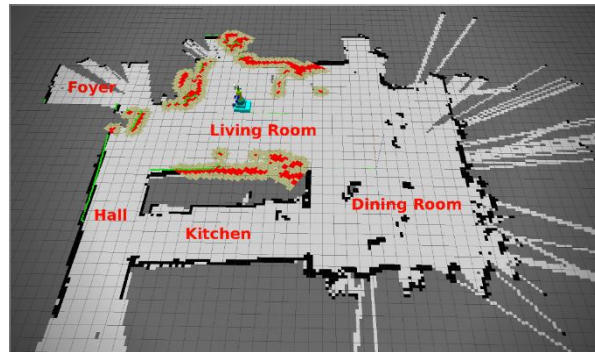
Industrial Applications



Automotive Applications



Surveillance/People
Counting Applications



SLAM (Simultaneous
Location and Mapping)



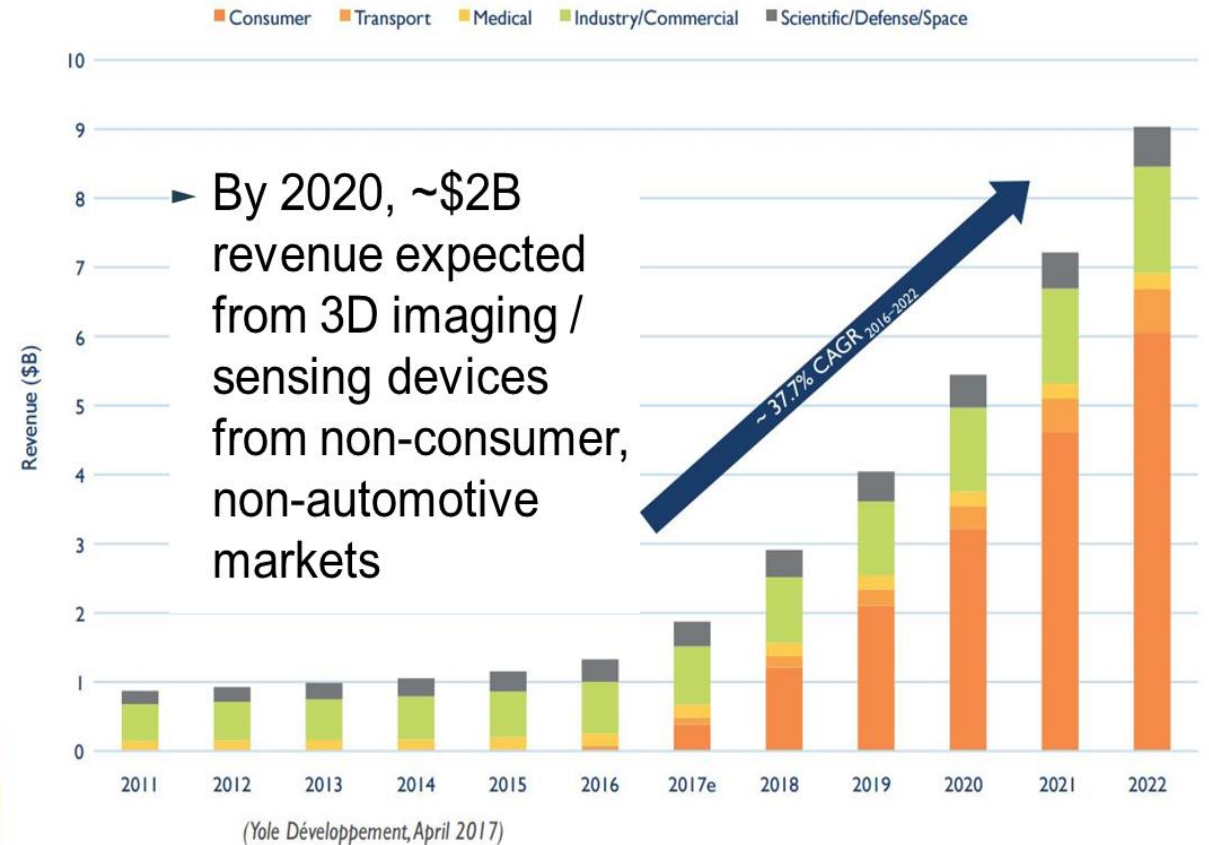
- ▶ Service Applications
- ▶ Home Robotics
- ▶ Warehouse Robots
- ▶ Autonomous Factories

ADI Time of Flight Depth Sensing Broad Market

- ▶ Strong pull towards broad market application areas for TOF, including:
 - Security / Surveillance / People counting
 - Robotics (Factory and AGV)
 - Logistics and Transport (supply chain management, machine vision, building management, etc.)



2011 - 2022 market forecast for 3D imaging & sensing devices



Depth Sensing Technologies

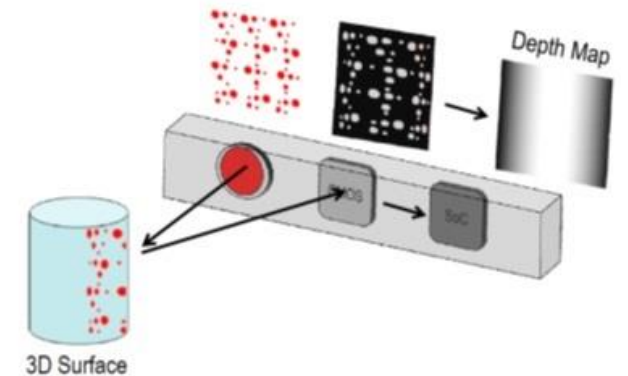
▸ Stereoscopic

- Used in smartphones and other applications
- Advantages: passive lighting system (only requires two cameras + application processor (AP))
- Disadvantages: doesn't work in dim or dark environments, object needs to have contrast to be detected (won't work on a white wall); longer distances require cameras to be farther apart

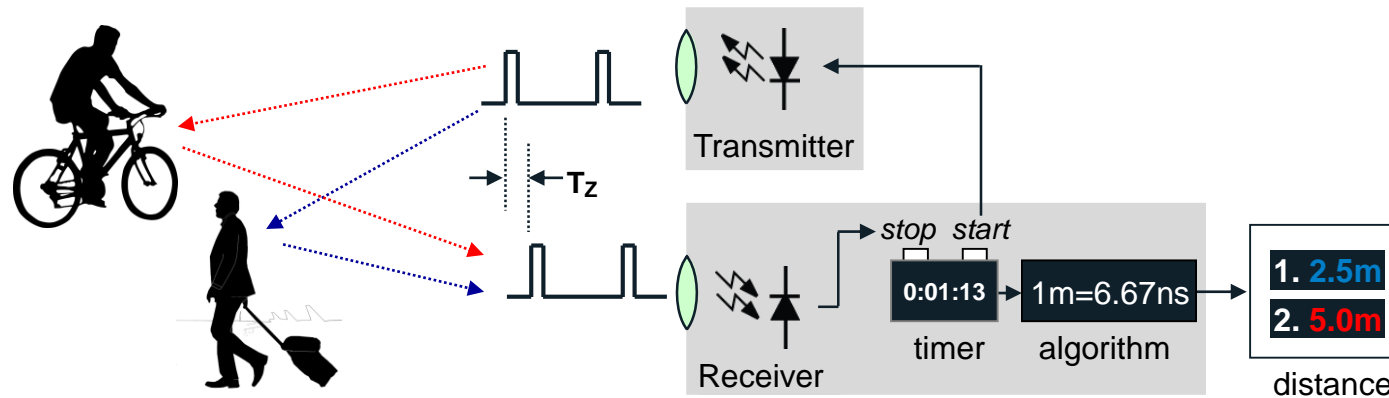


▸ Structured Light

- Used in Microsoft Kinect (1st Generation) and iPhones
- Advantages: very precise measurements at close distances (<1m)
- Disadvantages: does not work well in bright environments, longer distances (>2m); larger form factor; calibration difficulties during MP

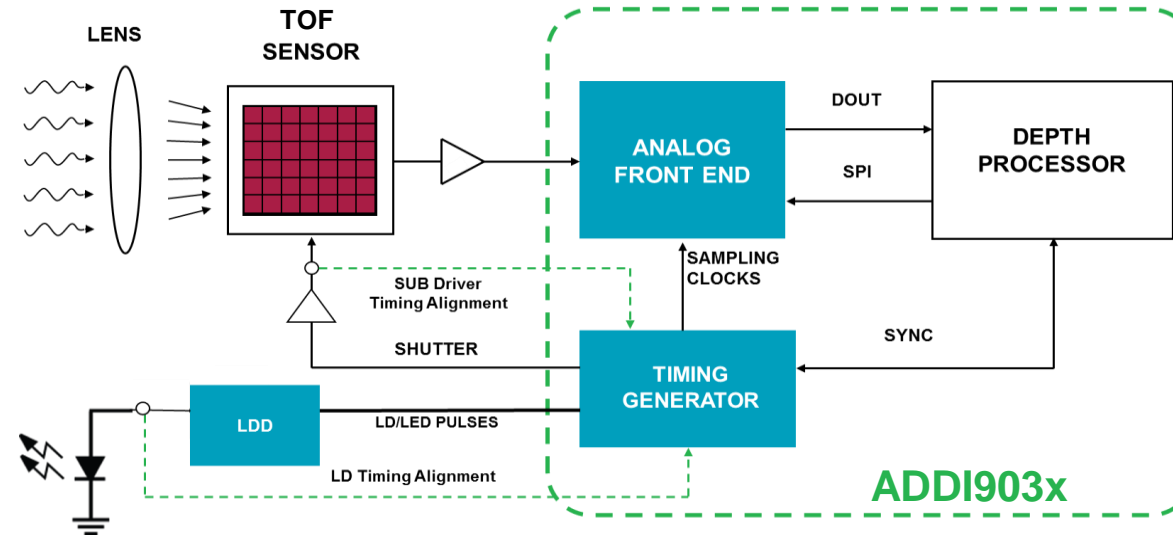


TOF Concept for 3D Depth Imaging



1. Transmit IR optical pulse
2. Synchronously receive the optical reflection
3. Measure the time delay between the Tx and Rx pulses:
 T_z = Time-of-Flight
4. Use the speed of light to calculate the target distance

Time-of-Flight (TOF) CCD Depth Camera

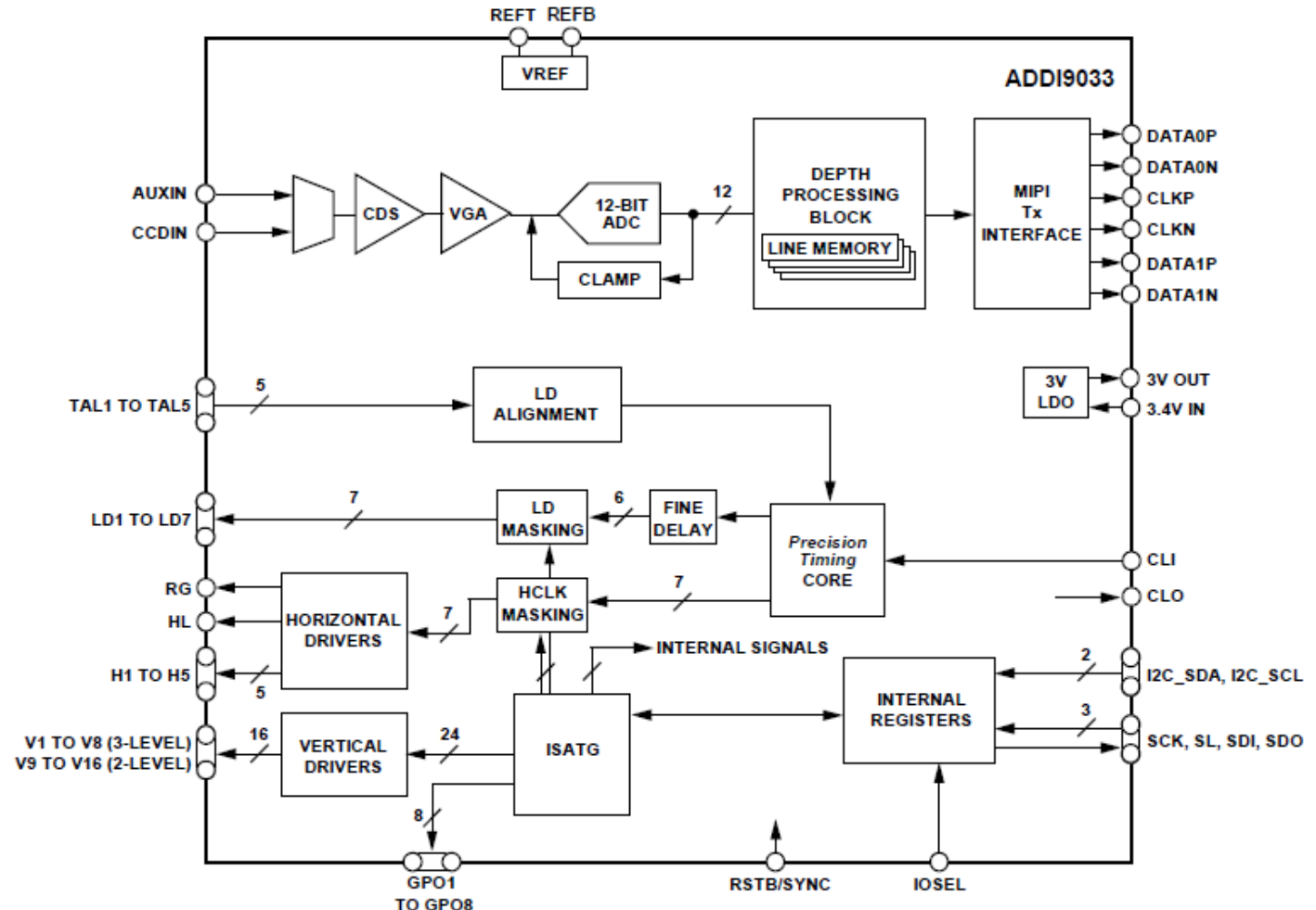


TOF CCD System Features

- ▶ **Wide dynamic range:** flexibility to detect close (<10cm) to far distances (>15m) depending on laser
- ▶ **Image and depth information** in QVGA / VGA resolution
- ▶ **940nm illumination** makes imaging possible in strong ambient light (see next slide)
- ▶ **More power efficient** at longer distances (smaller duty-cycle with pulsed TOF)
- ▶ **Global shutter sensor** – less motion blur
- ▶ **Multiple systems** can be operated in the same environment without interfering with each other

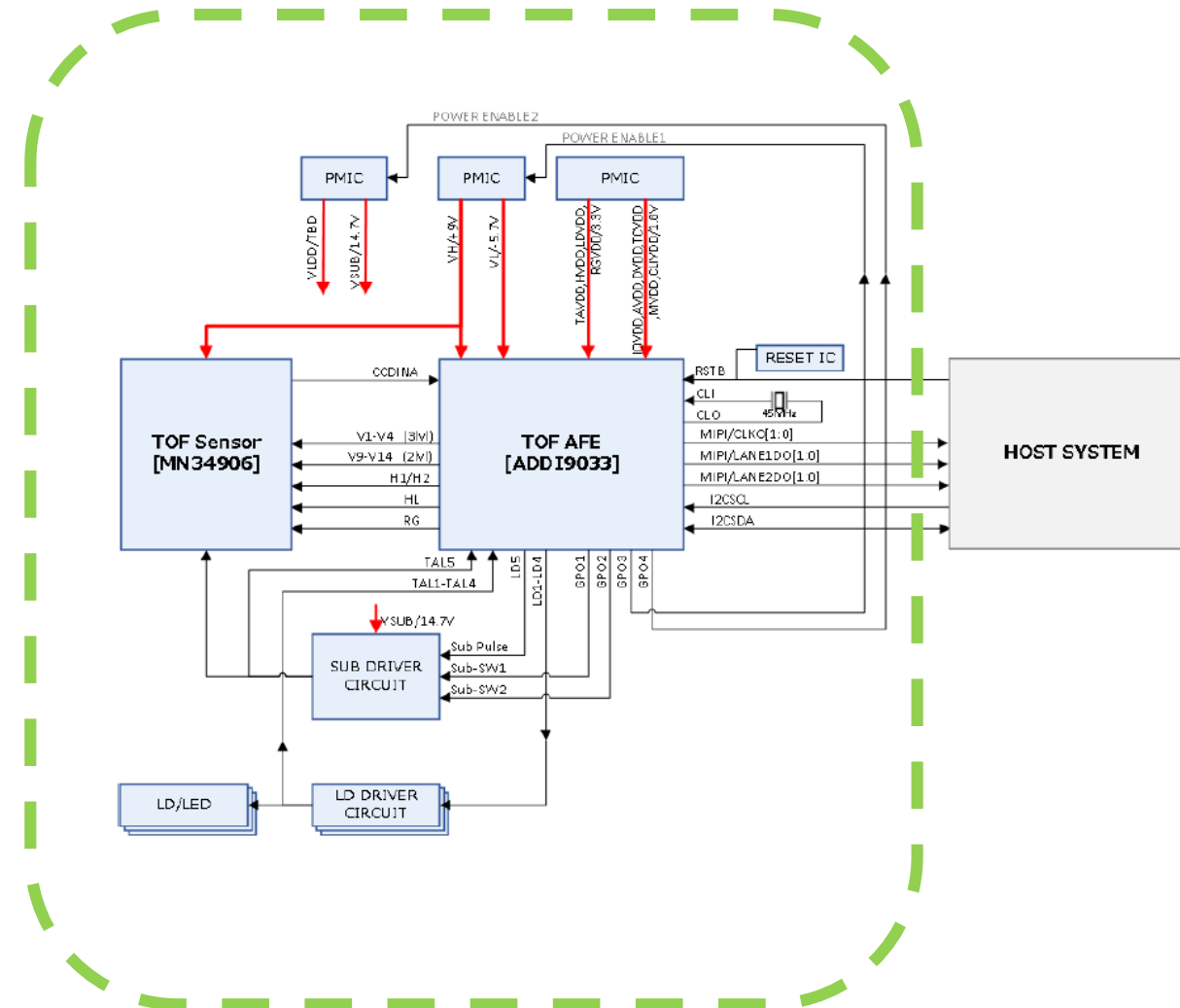
ADDI9033 / 5/ 6: TOF Signal Processor with Programmable Timing and V-driver

- ▶ 12-bit, 45MSPS AFE
- ▶ Internal Timing Generator
 - Integrated horizontal and vertical clock drivers
 - Integrated timing clock for laser diodes
 - *Precision timingtm* core with 174ps resolution
- ▶ Internal Depth Processor
- ▶ Closed feedback loop provides dynamic timing alignment
- ▶ ADDI9033
 - 8mm x 8mm, 12-ball CSP_BGA package
 - AEC-Q100 Grade 2 / ASIL-QM
- ▶ ADDI9035
 - SPI I/F only
 - 6mm x 6mm WLCSP
- ▶ ADDI9036
 - I2C I/F only
 - 6mm x 6mm WLCSP

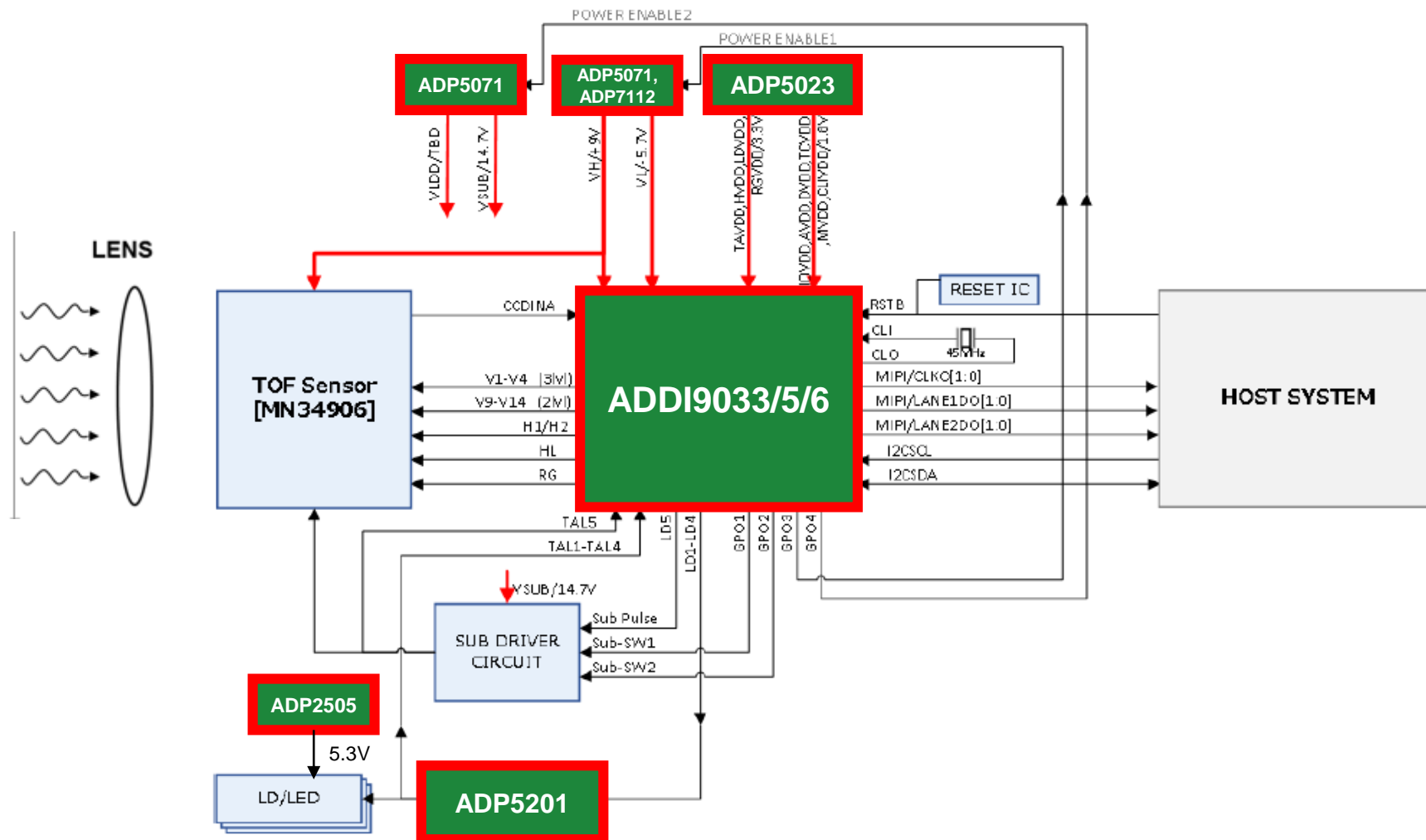


ADDI9033 Evaluation Board / TOF Module Availability

- **ADDI9033 Evaluation Board**
 - EB with ADDI9033, MN34906 (CCD), VCSEL (Princeton Optronics)
 - GUI Software
 - Windows / Linux SDK
- **TOF Module in Development**
 - Much smaller form factor
 - USB powered
 - Less flexibility than the evaluation board



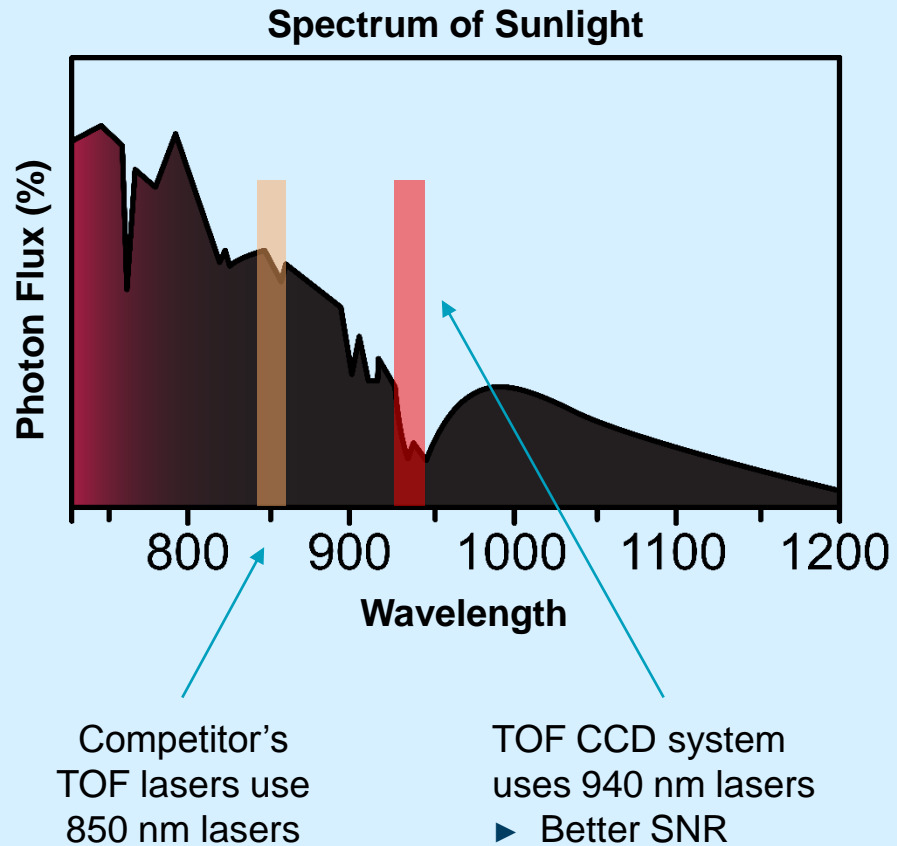
TOF System Block Diagram - Laser Diode Driver + VCSEL



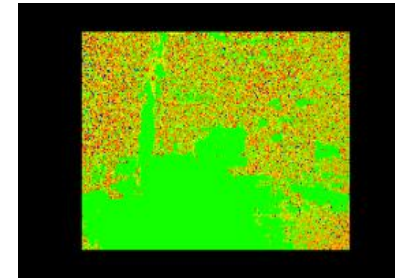
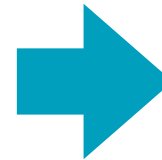
ADI TOF system level spec

| | | ADDI9035 | System Level advantage |
|----|--------------------------------|--|--|
| 1 | Pixel Size | 5.6 x 5.6 um | <ul style="list-style-type: none"> - Smaller chip size or higher resolution - Noise performance better than CMOS BSI |
| 2 | Resolution | VGA | Much better details especially in complex scenarios |
| 3 | Global Shutter | Yes | Better motion capturing |
| 4 | Pulsing scheme | 4ns ~ 22ns, duty cycle = 2.5% to 10% | Better optical power efficiency and thermal management |
| 5 | Sensitivity @ 940nm | Special design for 940nm | <ul style="list-style-type: none"> - Better outdoor performance - Higher QE than CMOS |
| 6 | Output Data | Depth only, Depth + IR, low power IR, Confidence map | Higher software flexibility |
| 7 | Embedded Processor | Flexible to support all system functions | Support more features such as Auto Exposure control, Wide Dynamic Range, Low power timing... etc |
| 8 | Temperature Drift | Hardware supported function | Self compensation in temperature difference. |
| 9 | Multi-system Anti-Interference | Hardware supported function | Multi system can be used in same space |
| 10 | Anti-EMI | Hardware supported function | |
| 11 | Calibration scheme | Ready to use | |

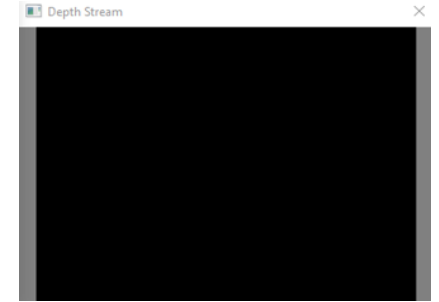
TOF CCD Camera Offers Superior Outdoor Performance



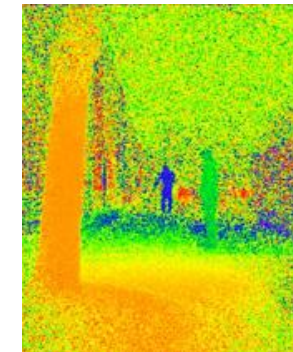
RGB



CMOS TOF



Structured Light

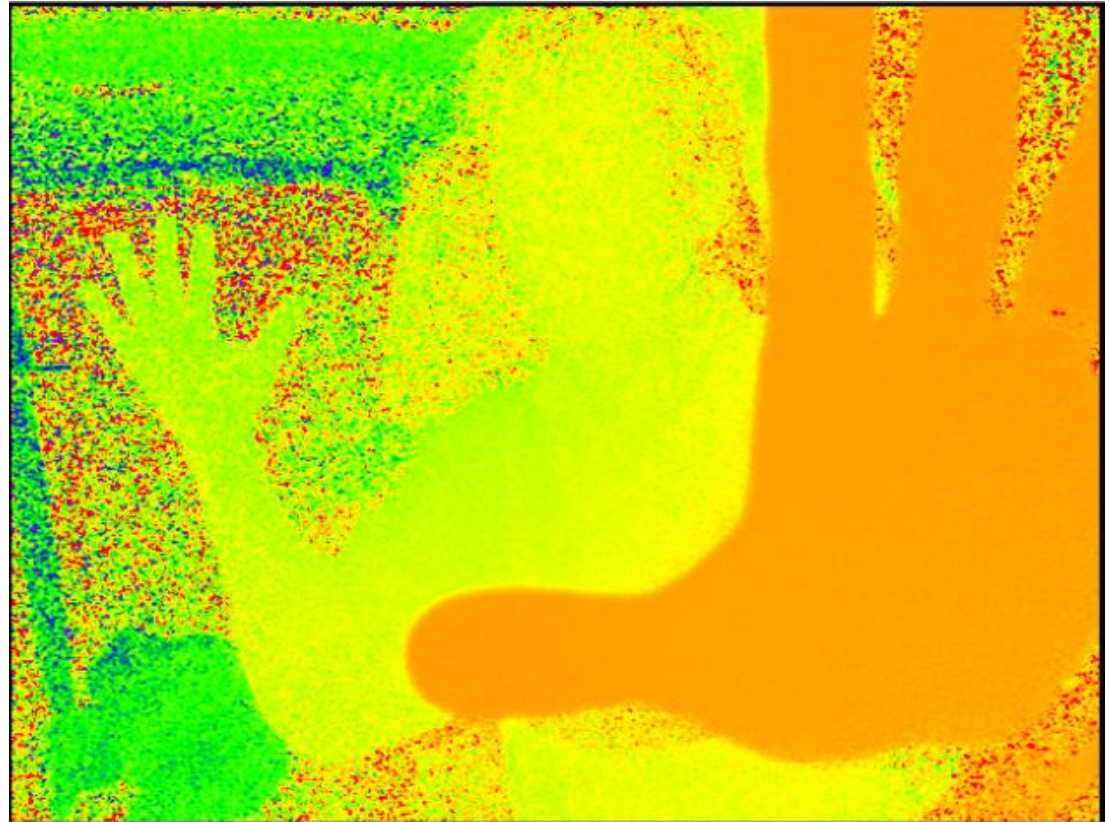


ADI TOF CCD

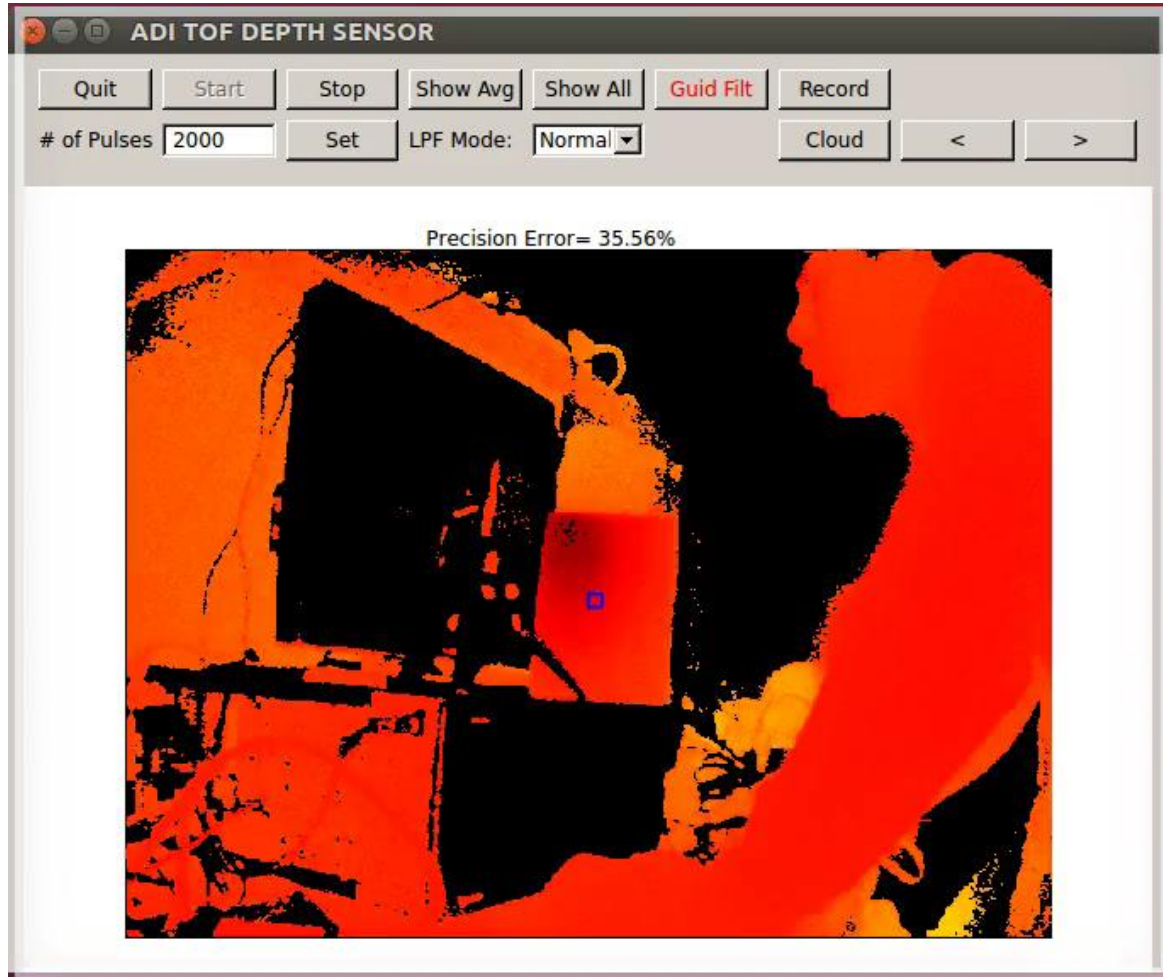
ADI TOF solution unique advantages

- ❑ **Higher sensitivity @ 940nm**
 - **Proved better outdoor performance**

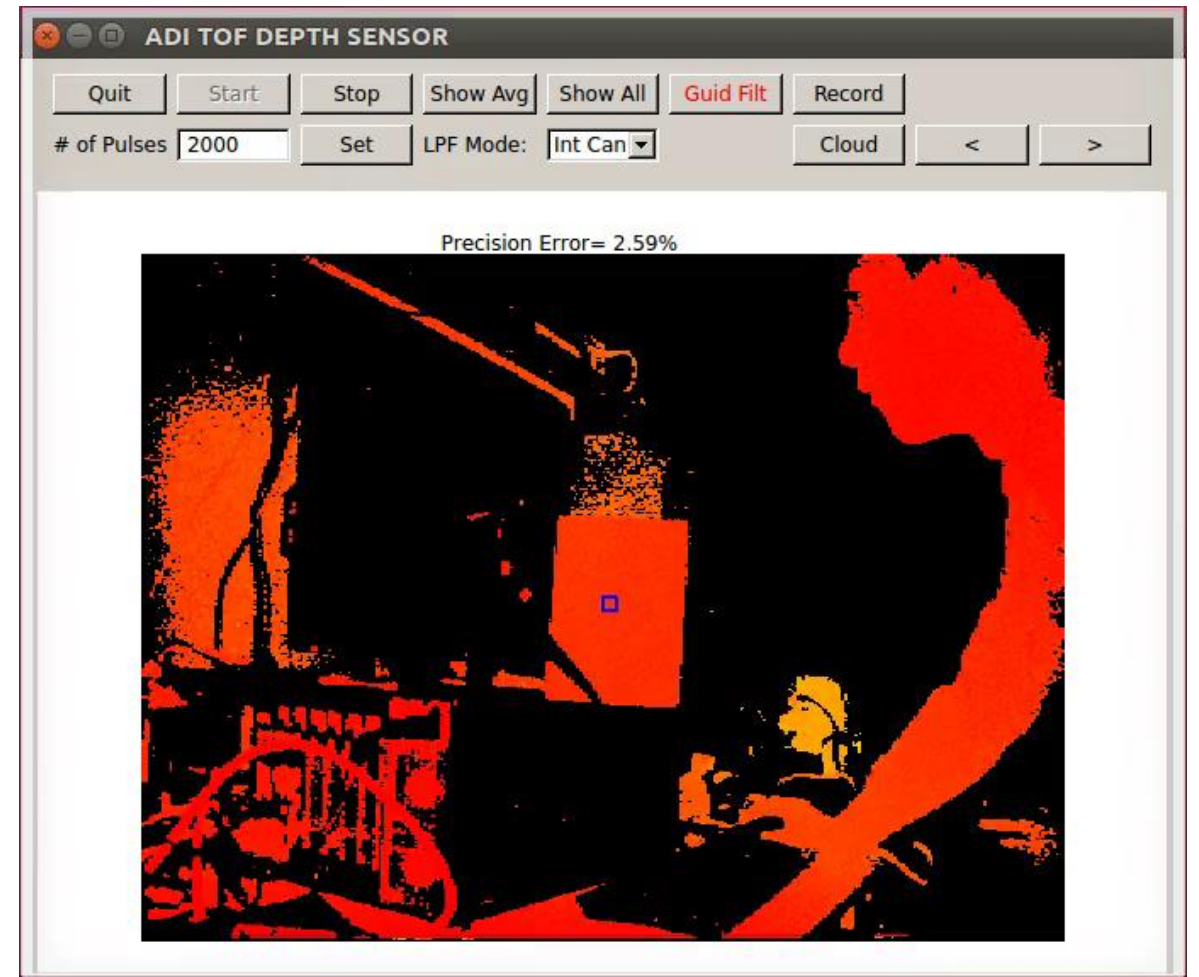
TOF CCD image inside car with 70K Lux
of light (>100K lux outdoors) (ADI)



Interference Cancellation (With / Without)

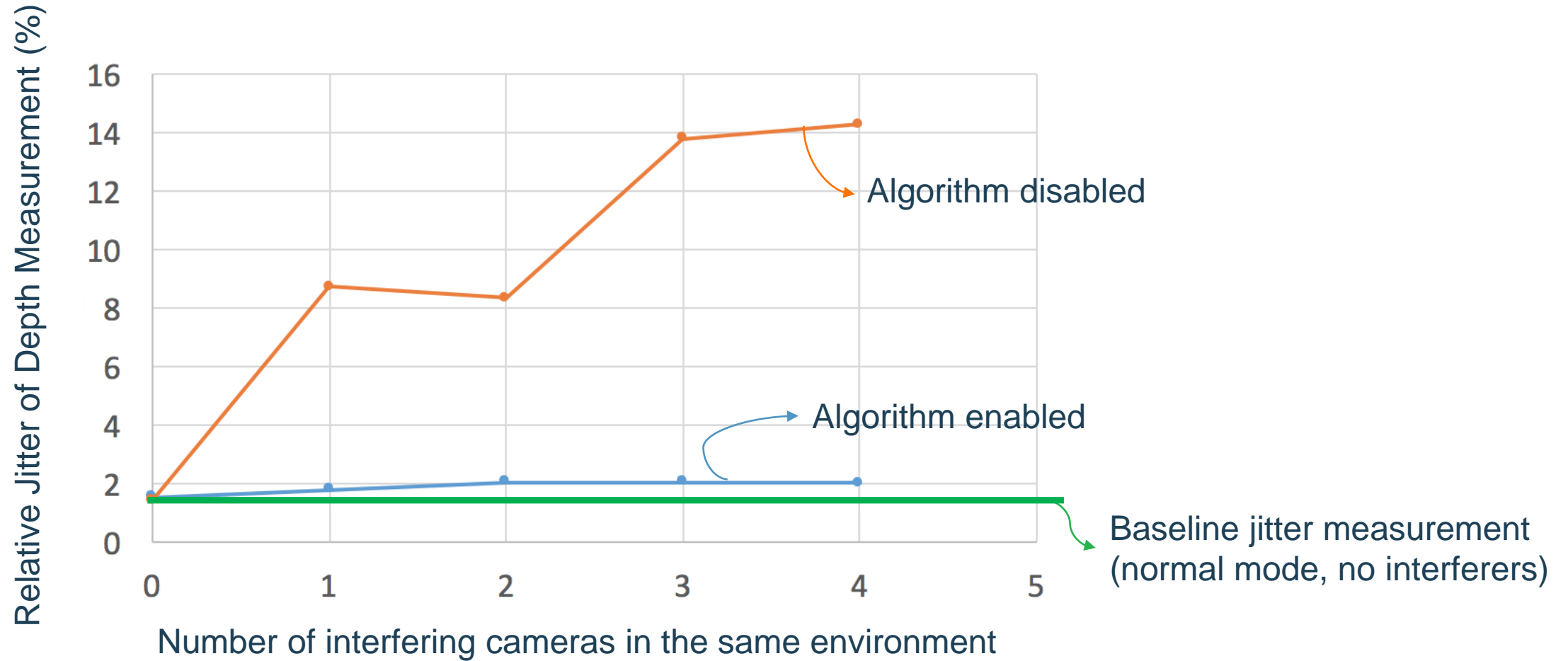


Without Interference Cancellation

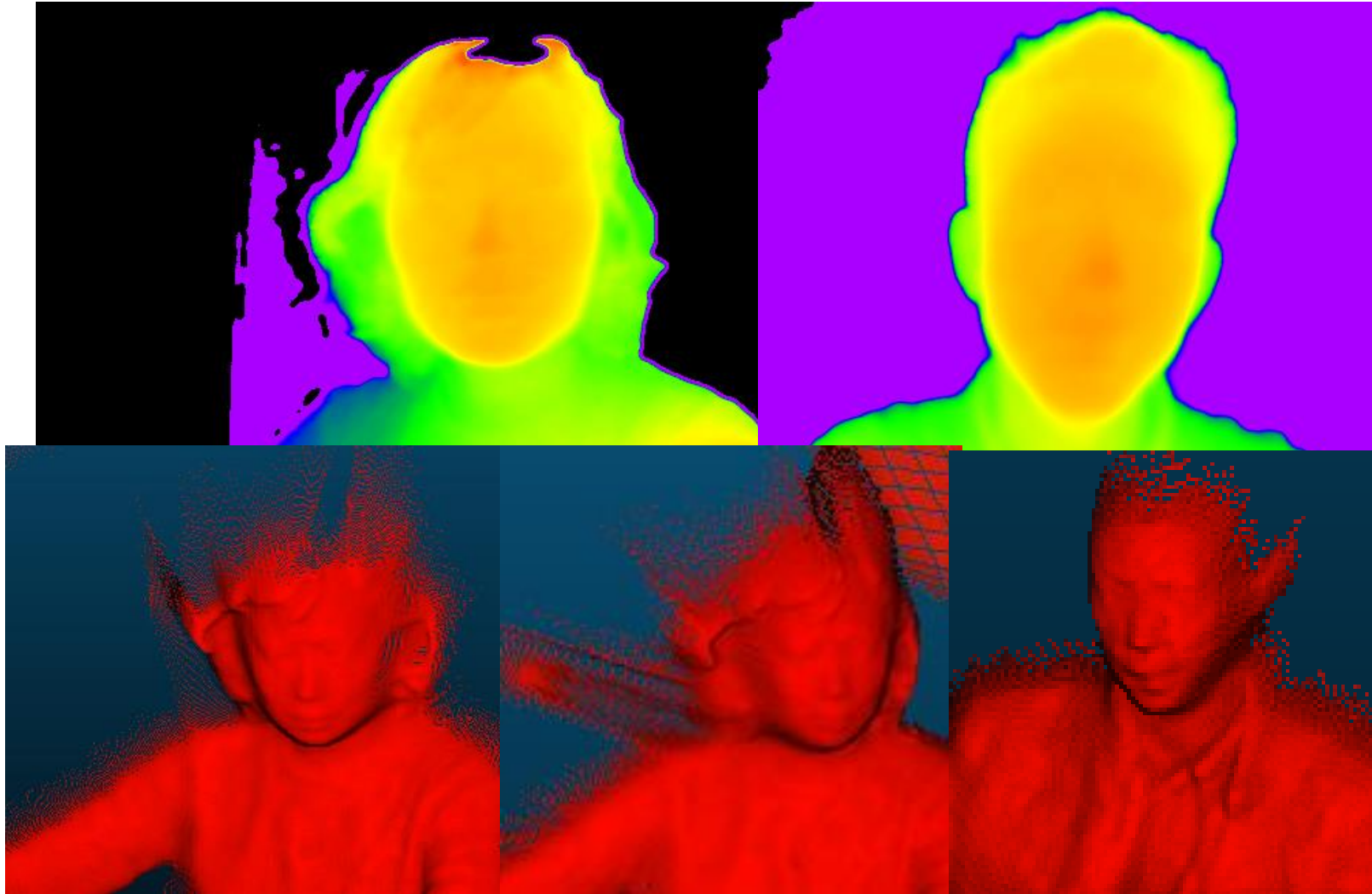


With Interference Cancellation

Interference Cancellation: Evaluation of Image Quality



ADI ToF depth image examples for facial recognition application



ADI ToF system level advantages analysis

| | ADI TOF | Other TOF | Structure light |
|---|--|--------------------|--------------------------------|
| Spacial resolution | High | Low | Low |
| Module size | Small | Small | Big |
| Sensing range | Near to long 0.2m ~ 3m+, MP ready | Near to mid ~2m | Near |
| Proven calibration scheme | Yes, <30s per module | TBD | Complicated calibration scheme |
| Multiple system interference cancellation | Yes | TBD | No |
| Facial recognition performance | Proven FAR <1/1,000,000 Financial security level (3 rd party algorithm) | TBD | TBD |
| Facial recognition speed | Best case <100ms Typical <350ms | TBD | >= 500ms |

Objective performance test result

| | | Raw | | Spatial Filter | |
|----------|---------------------|-------|-------|----------------|-------|
| | Target Reflectivity | 20% | 90% | 20% | 90% |
| Distance | | | | | |
| 1m | Depth Error | 1.36% | 0.71% | 0.53% | 0.73% |
| | Depth Noise Ratio | 2.50% | 1.16% | 1.73% | 0.79% |
| 1.5m | Depth Error | 0.91% | 0.435 | 0.81% | 0.57% |
| | Depth Noise Ratio | 2.87% | 1.34% | 1.86% | 0.93% |
| 2m | Depth Error | 0.47% | 0.38% | 0.60% | 0.34% |
| | Depth Noise Ratio | 3.30% | 1.58% | 2.18% | 1.10% |
| 2.5m | Depth Error | 0.71% | 0.36% | 0.50% | 0.40% |
| | Depth Noise Ratio | 3.84% | 1.76% | 2.56% | 1.17% |
| 3m | Depth Error | 0.42% | 0.41% | 0.39% | 0.40% |
| | Depth Noise Ratio | 6.50% | 1.80% | 3.70% | 1.23% |

TOF Hardware Roadmap

- All hardware can be promoted as a final product

Q1 2019

Q2 2019

Q3 2019

Q4 2019

2020

Pico



DCAM710
USB 2.0
DEPTH OUT ONLY
61 x 59 FOV
69mm x 25mm x 21.5mm
5 Meters
10 Meter Option
Recommended for new designs.
1 - \$199

FOR INTRO / DEMO:
ADI WILL ISSUE FREE TO
FAE FOR NEW OPPS
CUSTOMERS CAN BUY
ONLINE
CONTACT: COLM SLATTERY

Pico



MIPI INTERFACE
DEPTH OUT ONLY
Narrow FOV
60mm*28mm*11mm
6 Meter Range

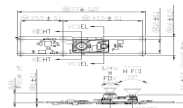
**AVAILABLE FOR
EVALUATION NOW**

**TOF
Modules
for
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ETHERNET
USB
WIFI
Wider FOV
5 Meters
AVAILABLE FOR
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1 - \$399
**EDGE NODE
PROCESSOR**



MIPI VERSION
1 - \$ 139
USB VERSION
1 - \$159

**AVAILABLE FOR
SALE FEB 2019**

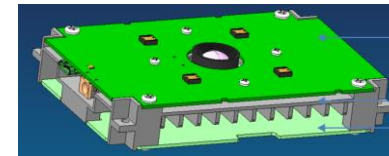
ANALOG
DEVICES



96 TOF PLATFORM
QUALCOMM
SNAPDRAGON

Q2/Q3 RELEASE

IN DEFINITION WITH PICO



INDUSTRIAL MODULE
USB & ETHERNET
61 x 59 FOV
5 Meters
3rd Party SDK
CAN BE SOLD
WITH/WITHOUT
HOUSING.

EST SAMPLES TBD
EST RELEASE

TOF SAFETY MODULE.
IN DEFINITION WITH
3RD PARTY

